Dual D-Type Positive Edge-Triggered Flip-Flop

HITACHI

Description

The HD74AC74 is a dual D-type flip-flop with Asynchronous Clear and Set inputs and complementary (Q, \overline{Q}) outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. Clock triggering occurs at a voltage level of the clock pulse and is not directly related to the transition time of the positive-going pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

Features

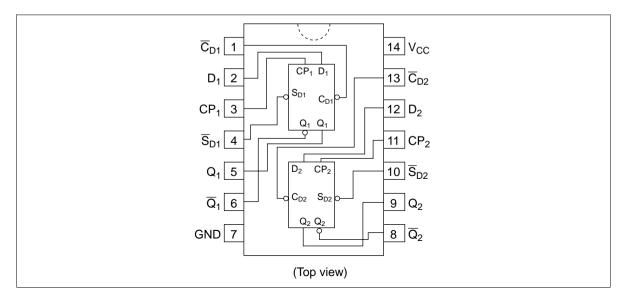
Asynchronous Inputs:

Low input to \overline{S}_D (Set) sets Q to High level Low input to \overline{C}_D (Clear) sets Q to Low level Clear and Set are independent of clock Simultaneous Low on \overline{C}_D and \overline{S}_D makes both Q and \overline{Q} High

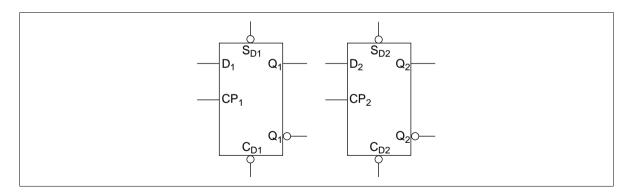
• Outputs Source/Sink 24 mA



Pin Arrangement



Logic Symbol



Pin Names

 D_1, D_2 Data Inputs CP_1, CP_2 Clock Pulse Inputs

 $\overline{C}_{D1}, \overline{C}_{D2}$ Crock Furse inputs $\overline{S}_{D1}, \overline{S}_{D2}$ Direct Clear Inputs
Direct Set Inputs

 $Q_1,\,\overline{Q}_1,\,Q_2,\,\overline{Q}_{\,2} \quad \text{ Outputs }$

Truth Table (Each Half)

Inputs				Outputs		
S _D	$\overline{\mathbf{C}}_{D}$	СР	D	Q	Q	
L	Н	Х	Х	Н	L	
Н	L	Х	Х	L	Н	
L	L	X	X	Н	Н	
Н	Н		Н	Н	L	
Н	Н		L	L	Н	
Н	Н	L	Х	Q_{0}	$\overline{Q}_{\scriptscriptstyle{0}}$	

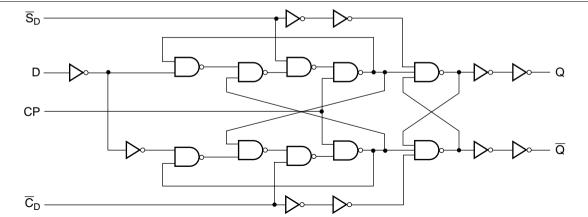
H : High Voltage Level
L : Low Voltage Level

X : Immaterial

: Low-to-High Clock Transition

 $Q_0(\overline{Q}_0)$: Previous $Q(\overline{Q})$ before Low-to-High Transition of Clock

Logic Diagram



Please note that this diagram is provised only for the understanding of logic operations and should not be used to estimate propagation delays.

DC Characteristics (unless otherwise specified)

Item	Symbol	Max	Unit	Condition
Maximum quiescent supply current	I _{cc}	40	μΑ	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, Ta = Worst case
Maximum quiescent supply current	I _{cc}	4.0	μΑ	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, Ta = 25°C

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AC Characteristics

			$Ta = +25^{\circ}C$ $C_{L} = 50 \text{ pF}$			Ta = -40° C to $+85^{\circ}$ C C _L = 50 pF		
Item	Symbol	V _{cc} (V)*1	Min	Тур	Max	Min	Max	Unit
Maximum clock	f _{max}	3.3	100	125	_	95	_	MHz
frequency		5.0	140	160	_	125	_	_
Propagation delay	t _{PLH}	3.3	1.0	8.0	12.0	1.0	13.0	ns
\overline{C}_{Dn} or \overline{S}_{Dn} to Q_n or \overline{Q}_n		5.0	1.0	6.0	9.0	1.0	10.0	_
Propagation delay	t _{PHL}	3.3	1.0	10.5	12.0	1.0	13.5	ns
\overline{C}_{Dn} or \overline{S}_{Dn} to Q_n or \overline{Q}_n		5.0	1.0	8.0	9.5	1.0	10.5	_
Propagation delay	t _{PLH}	3.3	1.0	8.0	13.5	1.0	16.0	ns
CP_n to Q_n or \overline{Q}_n		5.0	1.0	6.0	10.0	1.0	10.5	_
Propagation delay	t _{PHL}	3.3	1.0	8.0	14.0	1.0	14.5	ns
CP_n to Q_n or \overline{Q}_n		5.0	1.0	6.0	10.0	1.0	10.5	_

Note: 1. Voltage Range 3.3 is 3.3 V \pm 0.3 V Voltage Range 5.0 is 5.0 V \pm 0.5 V

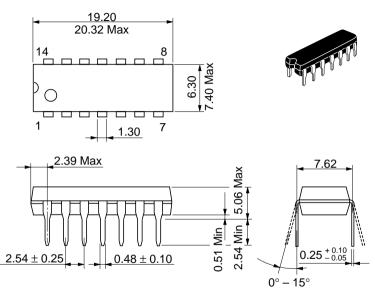
AC Operating Requirements: HD74AC74

			Ta = +25°C C _L = 50 pF		$Ta = -40^{\circ}C$ to +85°C $C_{L} = 50 \text{ pF}$	
Item	Symbol	V _{cc} (V)*1	Тур	Guaranteed	Minimum	Unit
Set-up time, HIGH or LOW	t_{su}	3.3	1.5	4.0	4.5	ns
D_n to CP_n		5.0	1.0	3.0	3.0	
Hold time, HIGH or LOW	t _h	3.3	-2.0	0	0	ns
D_n to CP_n		5.0	-1.5	0	0	
$\overline{CP_{n}}$ or \overline{C}_{Dn} or \overline{S}_{Dn}	t _w	3.3	3.0	5.5	7.0	ns
Pulse width		5.0	2.5	4.5	5.0	
Recovery time	t _{rec}	3.3	-2.5	0	0	ns
\overline{C}_{Dn} or \overline{S}_{Dn} to CP		5.0	-2.0	0	0	_

Note: 1. Voltage Range 3.3 is $3.3 \text{ V} \pm 0.3 \text{ V}$ Voltage Range 5.0 is $5.0 \text{ V} \pm 0.5 \text{ V}$

Capacitance

Item	Symbol	Тур	Unit	Condition
Input capacitance	C _{IN}	4.5	pF	$V_{cc} = 5.5 \text{ V}$
Power dissipation capacitance	C_{PD}	35.0	pF	$V_{cc} = 5.0 \text{ V}$



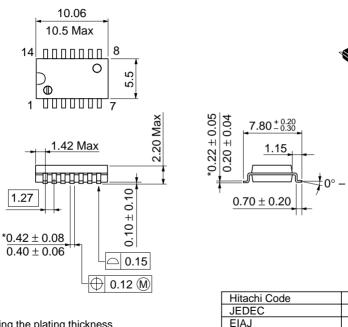
Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

FP-14DA

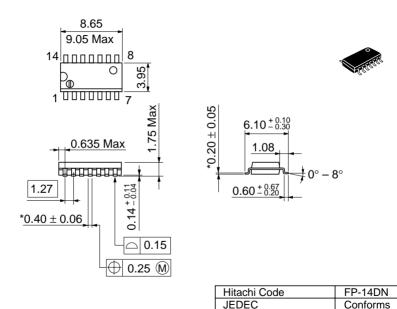
Conforms

0.23 g

Weight (reference value)



*Dimension including the plating thickness
Base material dimension



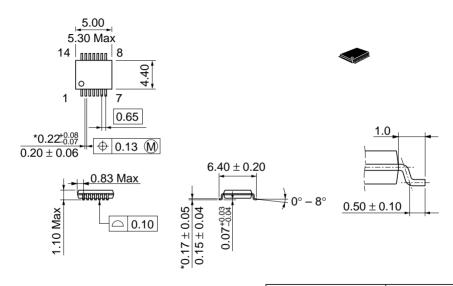
EIAJ

Weight (reference value)

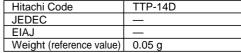
Conforms

0.13 g

*Pd plating



*Dimension including the plating thickness
Base material dimension



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